



#### RE900-02

- Epoxy fibre-glass FR4 1.50 mm
- Double-sided 35 µm Cu
- Plated through holes (PTH)
- Surface chem. Ni/Au with solder stop mask
- Adaption circuit board for TSOP I 28, 32, 40, 48 (0.50 mm)
- Hole diameter 1.00 mm
- Gerber data for manufacture of the soldering paste imprint will be provided free of charge on request
- Size: 26.50 x 43.64 mm

Modul-No.	Type	Pitch	Pin	Size (mm)
RE900-02	TSOP I	0.500 mm	28, 32, 40, 48	12.00 x 20.00